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PATENT ✓

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**In re Application of:**

Pai-Hung Pan

**Serial No.:** 09/944,506

**Filed:** August 30, 2001

**For:** TECHNIQUE FOR FORMING  
SHALLOW TRENCH ISOLATION  
STRUCTURE WITHOUT CORNER  
EXPOSURE AND RESULTING  
STRUCTURE

**Confirmation No.:** 4348

**Examiner:** Unknown

**Group Art Unit:** 2823

**Attorney Docket No.:** 2919.5US (96-499.2)

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CERTIFICATE OF MAILING

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November 11, 2002

Date

Amanda Holland  
Name (Type/Print)

**SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**

Box NON-FEE  
Commissioner for Patents  
Washington, D.C. 20231

Sir:

In compliance with the duty to disclose information material to patentability pursuant to 37 C.F.R. § 1.56, it is respectfully requested that this Supplemental Information Disclosure Statement be entered and the documents listed on attached Form PTO/SB/08 be considered by the Examiner and made of record. Copies of the listed documents are enclosed pursuant to 37 C.F.R. § 1.98(a).

In accordance with 37 C.F.R. § 1.97(g) and (h), filing of this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or an

admission that the information cited herein is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56(b). Further, no representation is made by Applicant herein that no other possible material information as defined in 37 C.F.R. § 1.56(b) exists.

DOCUMENTS

Other Documents

Lee, H., et al., "An Optimized Densification of the Filled Oxide for Quarter Micron Shallow Trench Isolation (STI)," IEEE Symposium on VLSI Technology 1996, pp. 158-159.

Applicant offers to supply any explanation or discussion of the documents that the Examiner feels is necessary or desirable and which is requested.

This Supplemental Information Disclosure Statement is filed within three (3) months of the filing date of the above-identified application, and no certification pursuant to 37 C.F.R. § 1.97(c) or a fee pursuant to 37 C.F.R. § 1.17(p) is required.

Respectfully submitted,



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BGP/jml

Enclosures: Form PTO/SB/08  
Cited Document



PTO/SB/08B(10-01)

Approved for use through 10/31/2002, OMB 0651-0031

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Substitute for form 1449A/PTQ

## **INFORMATION DISCLOSURE STATEMENT BY APPLICANT**

(use as many sheets as necessary)

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1 of 1

*Complete if Known*

Application Number	09/944,506
Filing Date	August 30, 2001
First Named Inventor	Pai-Hung Pan
Group Art Unit	2823
Examiner Name	Unknown
Attorney Docket Number	2919.51JS (96-499.2)

## OTHER PRIOR ART -- NON PATENT LITERATURE DOCUMENTS

Examiner Signature		Date Considered	
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**<sup>1</sup>EXAMINER:** Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

<sup>1</sup> Unique citation designation number (optional). <sup>2</sup> Applicant is to place a check mark here if English language Translation is attached.

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